

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	0	438/646.ccls. and (@ad<"20020731") and ((heat or cur\$3 or "Uv") with (adhesive or poyimide or tape or (no adj flow)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/23 10:32
L2	77	438/646.ccls. and (@ad<"20020731")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/23 10:23
L3	67	L2 and (encapsulant or epoxy or fill\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/23 10:24
L4	68	L2 and (encapsulate or resin or encapsulant or epoxy or fill\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/23 10:23
L5	1042	438/464.ccls. and (@ad<"20020731")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/23 10:33
L6	178	L5 and (encapsulant or epoxy or fill\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/23 10:29
L7	138	L5 and ((heat or cur\$3 or "Uv") with (adhesive or poyimide or tape or (no adj flow)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/23 10:30
L8	67	L7 not L6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/23 10:30

L9	141	438/464.ccls. and (@ad<"20020731") and ((heat or cur\$3 or "Uv") with (release or adhesive or poyimide or tape or (no adj flow)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/23 10:33
L10	141	L9 and (@ad<"20020731")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/23 10:34
L11	3	L10 not L7	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/23 10:36
L12	381	438/67,68,107,455,458.ccls. and (@ad<"20020731") and ((heat or cur\$3 or "Uv") with (release or adhesive or poyimide or tape or (no adj flow)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/23 10:34
L13	141	L10 and (@ad<"20020731")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/23 10:37
L14	110	L13 and ((remov\$3 or peel\$3 or pull\$3 or etch\$4 or polish\$3 or "cmp" or grind or laser) with (substrate or transfer or carrier or wafer or handle or chuck or holder or board or interposer))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/23 10:37
L15	0	L14 not L10	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/23 10:38
L16	1	L14 not L7	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/23 10:36

L17	381	L12 and (@ad<"20020731")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/23 10:37
L18	110	L13 and ((remov\$3 or peel\$3 or pull\$3or etch\$4 or polish\$3 or "cmp" or grind or laser) with (substrate or transfer or carrier or wafer or handle or chuck or holder or board or interposer))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/23 10:37
L19	275	L12 and ((remov\$3 or peel\$3 or pull\$3or etch\$4 or polish\$3 or "cmp" or grind or laser) with (substrate or transfer or carrier or wafer or handle or chuck or holder or board or interposer))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/23 10:37